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Chou et al.

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(54) **BRIDGE RECTIFIER PACKAGE WITH HEAT SINK**

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(**) Term: **14 Years**

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(22) Filed: **Apr. 6, 2010**

Related U.S. Application Data

(62) Division of application No. 29/321,381, filed on Jul. 15, 2008, now Pat. No. Des. 616,387, which is a division of application No. 29/267,653, filed on Oct. 19, 2006, now Pat. No. Des. 573,116.

(51) **LOC (9) Cl.** **13-03**
(52) **U.S. Cl.** **D13/182**
(58) **Field of Classification Search** D13/179, D13/182; 165/80.3, 104.33, 151, 122, 185; 257/706, 707, 718–722, 177, 347; 361/687, 361/695, 697, 700, 702, 704, 709, 710, 711, 361/719
See application file for complete search history.

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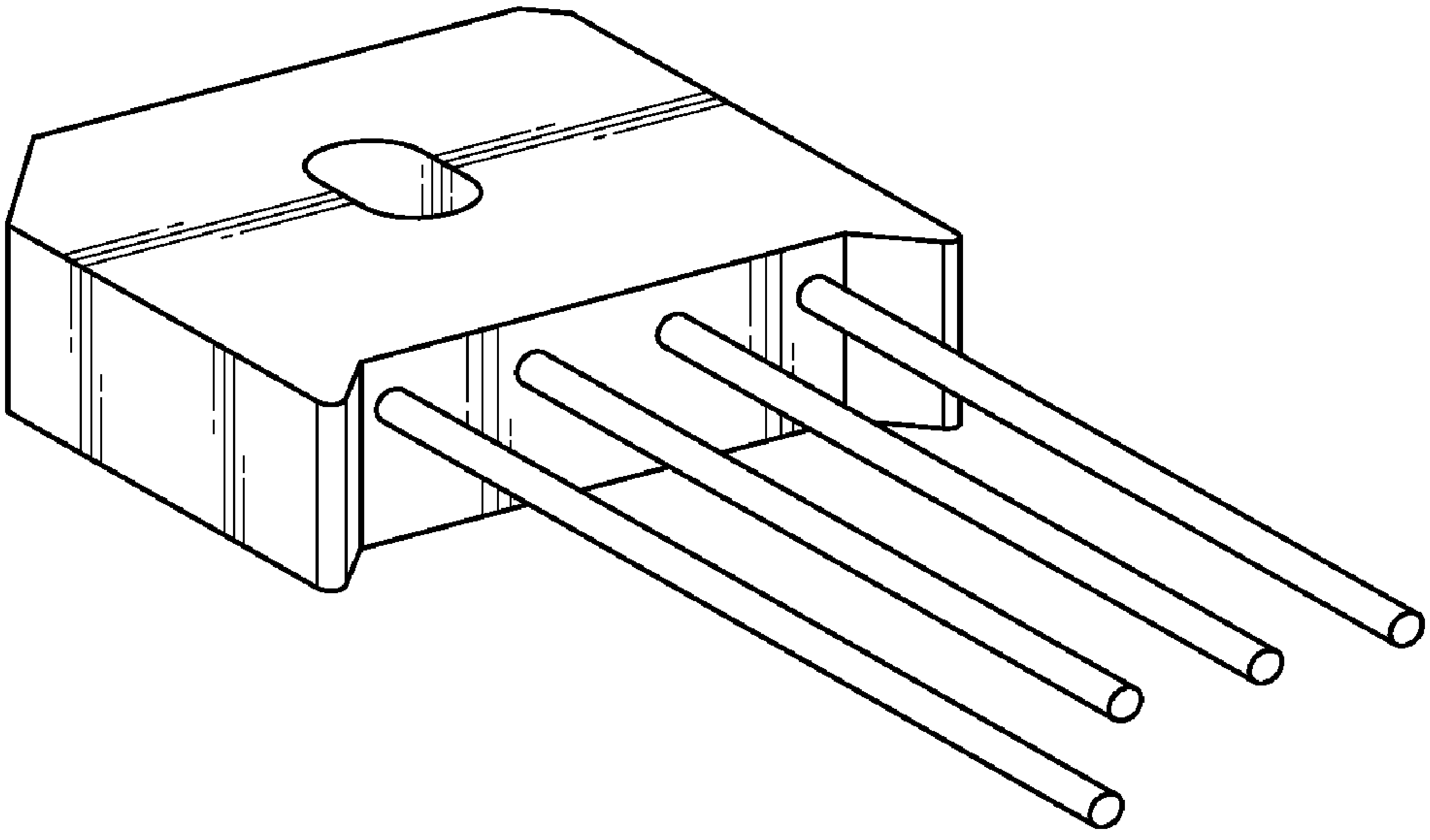
(57) **CLAIM**

The ornamental design for a new bridge rectifier package with heat sink, as shown and described.

DESCRIPTION

FIG. **1** is a left, top perspective view of a new bridge rectifier package with heat sink showing our new design;
FIG. **2** is a top view thereof;
FIG. **3** is a bottom view thereof;
FIG. **4** is a left view thereof;
FIG. **5** is a right view thereof;
FIG. **6** is a front view thereof; and,
FIG. **7** is a back view thereof.

1 Claim, 2 Drawing Sheets



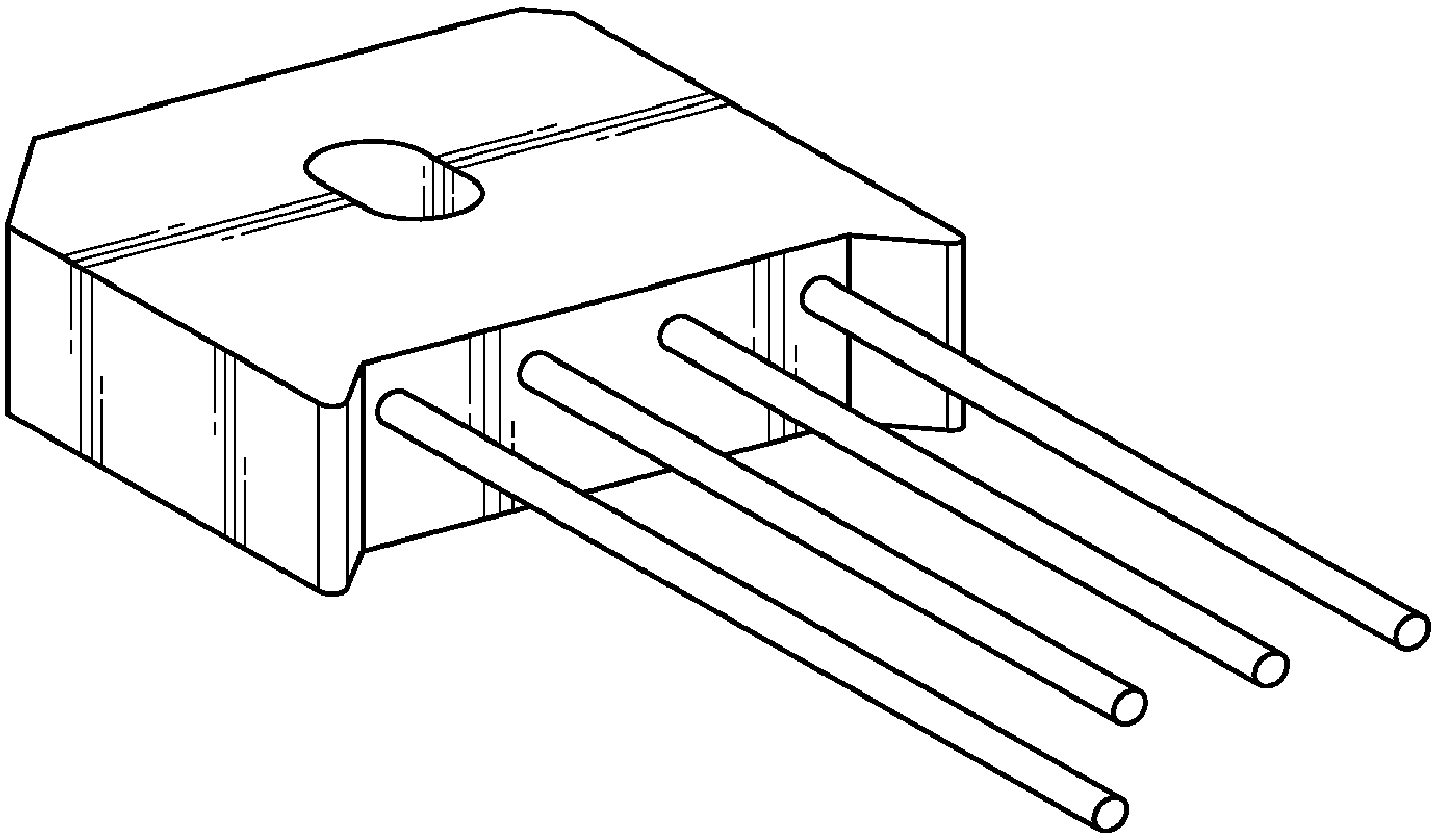


FIG. 1

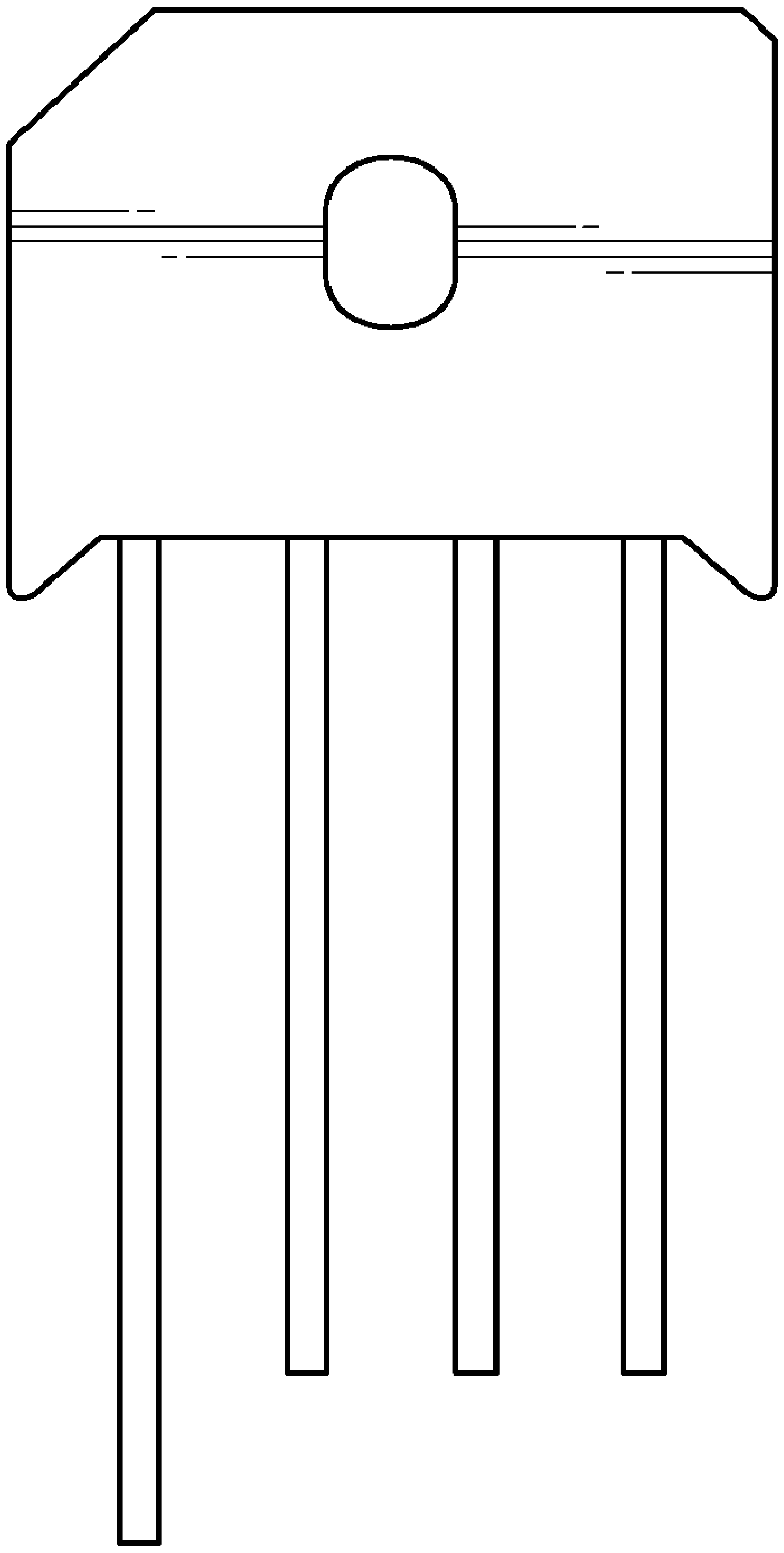


FIG. 2

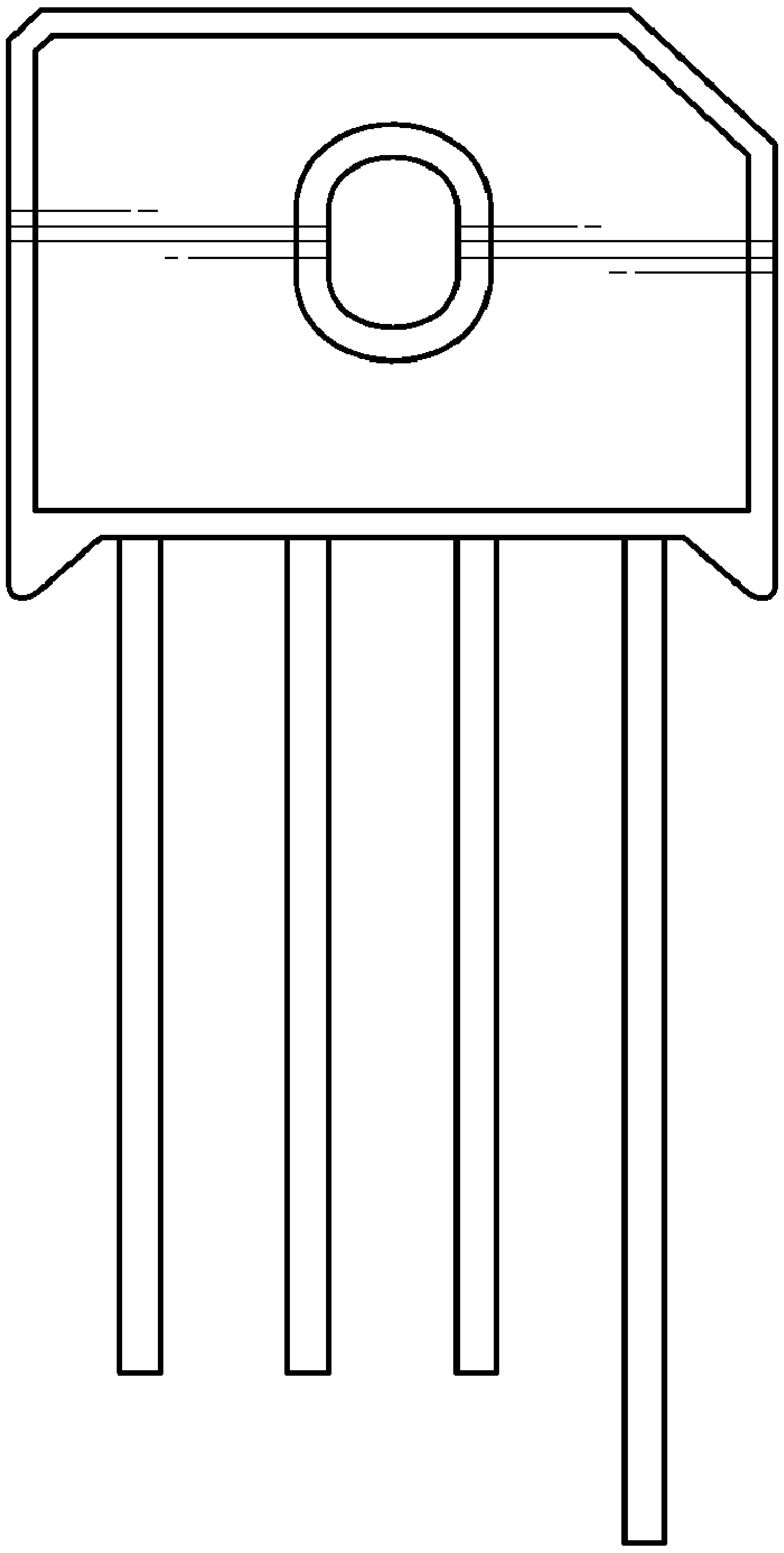


FIG. 3

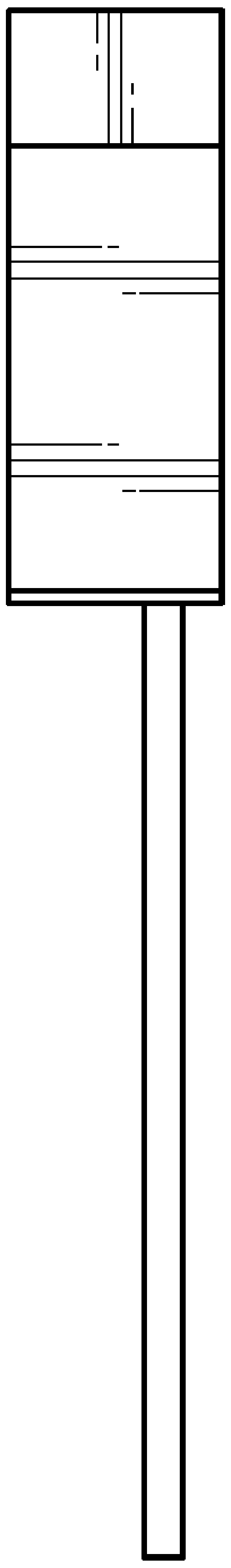


FIG. 4

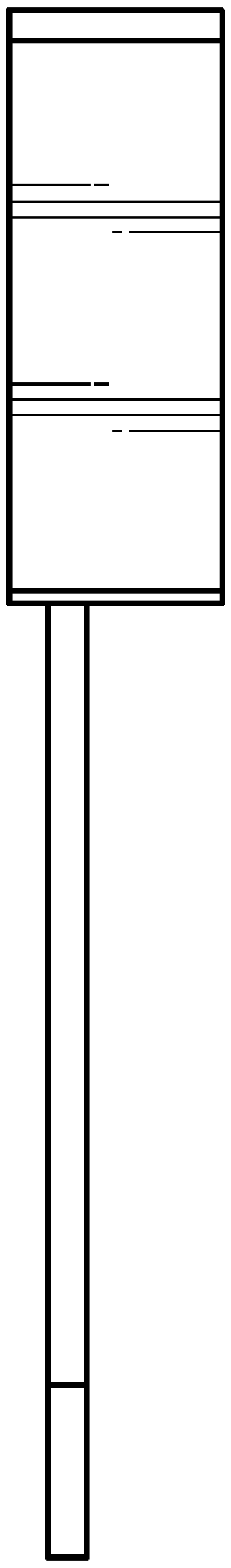


FIG. 5

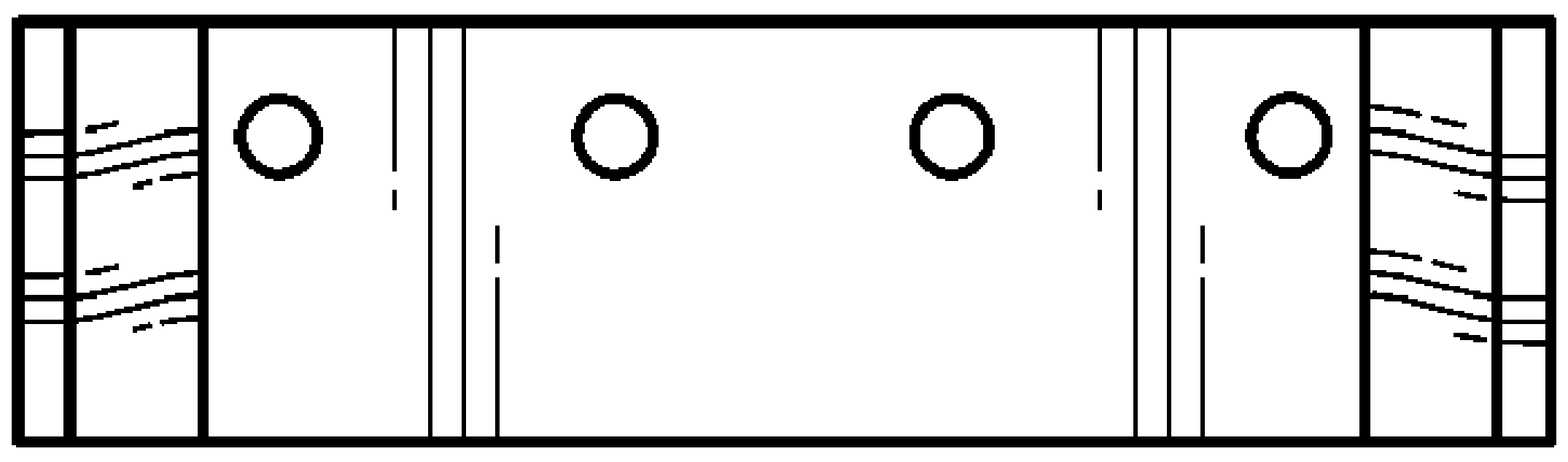


FIG. 6

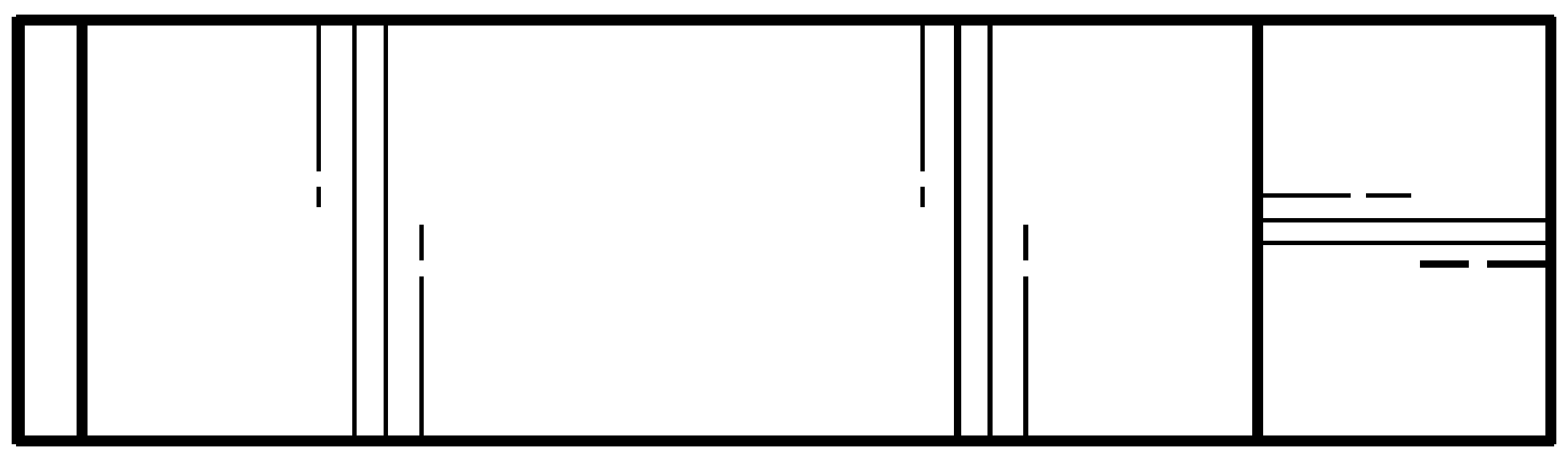


FIG. 7